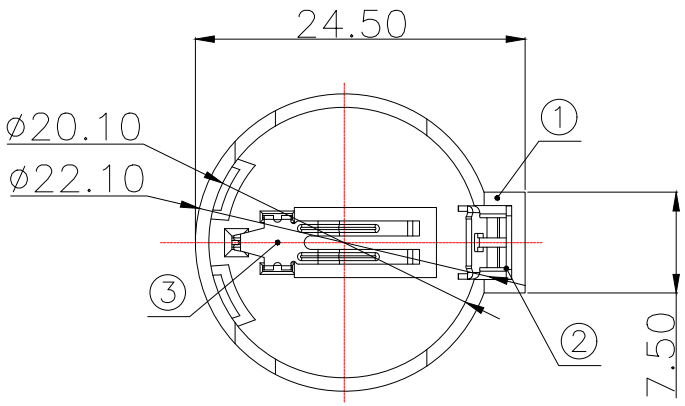
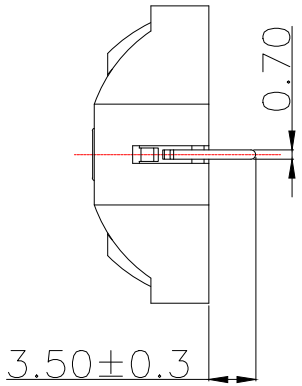
RoHs 环保

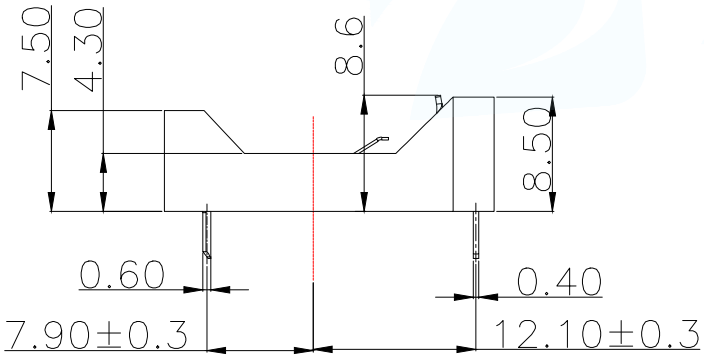
A型

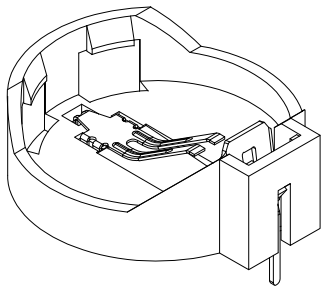
MAPX	MODIFICATION	DATE	DRAW	APPROVE

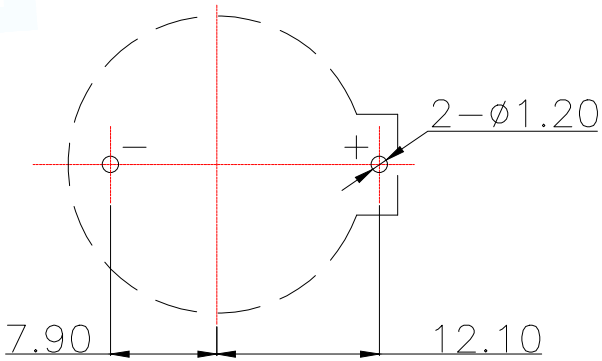




NOTE:
1.MATERIAL:
a.HOUSING:PBT UL 94V-0
b.CONTACT:PHOSPHOR BRONZE
(SURFACE PLATING:Sn=100u"-120u")
2.ELECTRIC:
a.CONTACT RESISTANCE: 50 MILLIOHMS MAX
b.INSULATION RESISTANCE: 100 MEGA OHMS MIN
c.DIELECTNIC VOLTAGE: 500V AC FOR ONE MINUTE
d.OPERATING TEMPERATURE: -25°C~ +85°C







PCB Layout Diagram
Top View

NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR
3	TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.20mm	Sn-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.40mm	Sn-Plating
1	HOUSING	1	PBT	BLACK

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co,Ltd	
UNLESS OTHERWISE SPECIFED TOLERANCES			TITLE: Sn DIP 环保
DECIMALS:	ANGLES:		PAR: BS-0202-DK-0B
X.X±0.30	X.°±5°		DWN:
X.XX±0.25	X.X°±1°		CHKD:
X.XXX±0.15		CUSTOMER COPY	APVD:
			SCALE N:A / UNIT:MM
			SIZE:A4 / SHEET:1F1 / REV:A

Unikeyic Electronics

Global Electronic Components Distributor

Click to view pricing, inventory, delivery, and lifecycle information:

XUNPU:

WAFER-XH2.54-2PLB WAFER-XH2.54-5PZZ PCIE-52P40H DSPV-02-LD-GET WAFER-100L-3P
WAFER-GH1.25-9PWB WAFER-MX1.25B-12PZZ WAFER-PH2.0-8PWZ MCS-302S-C1 TS-1009B-AR05026
PHB2.0-02-24PWZ TS-1009-AR03826 WAFER-MX3.0-14PWZ WAFER-XH2.54-4PLB DP-001-C-J
FPC-0.5AS-6PWBH20 FPC-0.5AX-8PWBH20 WAFER-MX1.25-4PWZ WAFER-PH2.0-4PZZ
PH2.54-07-06PWD SMA-KE-347A-H13.5-P TF-123-ARP9H17 WAFER-MX1.25B-10PWZ
WAFER-PH2.0-2PJK SIM-116-ACP7 DSHP-05-TJ-GER DSIC-01-LD-GET FPC-0.5HF-12PWBH20
WAFER-100W-4P WAFER-MX1.25B-2PZZ